# EAST Search History

## EAST Search History (Prior Art)

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|---|---|---|---|---|---|---|
| L1 | 55 | (Sputtering vacuum adj2 deposition) near5 polishing with (circuit wiring) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2011/07/08 10:52 |
| L2 | 8 | (Sputtering vacuum adj2 deposition) near5 roughness with (circuit wiring) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2011/07/08 10:55 |
| L3 | 183 | (Sputtering vacuum adj2 deposition evaporation) with (reduc$3 decreas$3) near5 roughness | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2011/07/08 10:57 |
| L4 | 69 | (Sputtering vacuum adj2 deposition evaporation) with (reduc$3 decreas$3) near5 surface adj roughness | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2011/07/08 10:57 |
| L5 | 0 | (Sputtering vacuum adj2 deposition evaporation) with (reduc$3 decreas$3) near5 surface adj roughness same foil | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2011/07/08 11:04 |
| L6 | 22 | ("20020060090" \| "20020155021" \| "20030006063" \| "20030096082" \| "20030108766" \| "4959507" \| "5273938" \| "6309528" \| "6476330" \| "6558231" \| "6750144").PN. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2011/07/08 11:15 |

| L7 | 387 | Multilayer near2 laminate and circuit adj board and laminating | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2011/07/08 11:17 |
|----|-----|---|---|----|----|---|
| L8 | 3 | Multilayer near2 laminate and circuit adj board and laminating and (reduc $3 decreas$3) near5 surface adj roughness | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2011/07/08 11:17 |
| L9 | 64 | circuit adj board and laminating and (reduc $3 decreas$3) near5 surface adj roughness | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2011/07/08 11:19 |
| L10 | 114 | Circuit adj (pattern trace) and Multilayer near2 laminate and circuit adj board and laminating | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2011/07/08 11:20 |
| L11 | 788 | (Sputtering vacuum adj2 deposition evaporation) with copper adj foil | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2011/07/08 11:45 |
| L12 | 34 | (Sputtering vacuum adj2 deposition evaporation) with copper adj foil with roughness | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2011/07/08 11:45 |
| L13 | 75 | (Sputtering vacuum adj2 deposition evaporation) with surface near5 copper adj foil | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2011/07/08 11:46 |
| L14 | 2 | (Sputtering vacuum adj2 deposition evaporation) with surface near5 copper adj foil same roughness | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2011/07/08 11:57 |

| L15 | 52 | (Sputtering vacuum adj2 deposition evaporation) with copper adj foil same roughness | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2011/07/08 11:57 |
| L16 | 34 | (Sputtering vacuum adj2 deposition evaporation) with copper adj foil with roughness | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2011/07/08 11:57 |
| L17 | 178 | (Sputtering vacuum adj2 deposition evaporation) with (reduc$3 decreas$3) with surface adj roughness | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2011/07/08 12:01 |

**EAST Search History (Interference)**

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**7/8/2011 1:07:01 PM**
**C:\ Documents and Settings\ Ivan1\ My Documents\ EAST\ Workspaces\ 10667491**
**polishing circuit trace.wsp**